# Development of 100W Solid State Power Amplifier at $13.56 \pm 1 \mathrm{MHz}$ 

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#### Abstract

Project aim is the development of a common source class B, cwrf amplifier by using MOSFET. The work includes literature survey, concept, simulation, design, fabrication and testing of the power amplifier. This single stage amplifier of more than 100 W output and gain 13 dB needs development in the frequency range of $13.56 \pm 1 \mathrm{MHz}$. A temperature sensor at the heat sink mounting must be added along with necessary wiring to switch off the dc supply and thereby protecting the circuit in case of overheating. The ultimately developed amplifier needs testing for the frequency response, power gain and output wave shapes etc. by using a set of appropriate instruments.


Keywords- Solid State Power Amplifier, L-section, MOSFET, Class B

## I. Introduction

An amplifier is used to increases the voltage, current or power of a signal. Amplification can be done with a vacuum tube or transistor. In transistors, the electrons passes through the solid material therefore named solid state devices. In power amplifier, voltage and current level of the signal is increased. There are four types of the power amplifier namely class $A$, class B, class AB and class C. As specified, one MOSFET based class B power amplifier is planned to be used. In the output circuit, the amplified positive half cycle of the input signal is converted in to the full cycle by flywheel effect due to tank circuit.

## II. Design Methodology of the 100W SSPA

## A. Specifications:

TABLE I. SPECIFICATONS REQUIREMENT OF THE 100W SSPA

| Sr. No. | Parameters | Values |
| :---: | :---: | :---: |
| 1. | Center Frequency | 13.56 MHz |
| 2. | Bandwidth | $\pm 1 \mathrm{MHz}$ |
| 3. | Output power | More than100W |
| 4. | Gain | More than13dB |
| 5. | Efficiency | More than $50 \%$ |
| 6. | Harmonics | Less than 20 dB |

## B. Selection of the appropiate transistor

The specifications of available MOSFETS in the required frequency range and having appropriate power ratings are studied. The MACOM make n-channel enhancement type MOSFET MRF151 is selected due to its suitable ratings. The stability factor of this MOSFET is found to be 3.1.

## III. DESIGN OF THE INPUT CIRCUIT

From the manufacturer's data of MRF151, input impedance $\mathrm{Z}_{11}=(4.5-\mathrm{j} 4.6) \Omega$ and $\mathrm{R}_{\mathrm{G}}=50 \Omega$. The source impedance is $(50+\mathrm{j} 0) \Omega$ and the load impedance is $(4.5-\mathrm{j} 4.6) \Omega$.


Figure 1: Circuit of input impedance matching
L-section is used for the impedance matching.
As $\mathrm{R}_{\mathrm{G}}>\mathrm{R}_{\mathrm{L}}$ thus $Q=\sqrt{\frac{R_{g}}{R_{L}}-1}$.
Using given values of $\mathrm{R}_{\mathrm{G}}$ and $\mathrm{R}_{\mathrm{L}}$ we get, $\mathrm{Q}=3.18$.

Now, $\mathrm{X}_{\mathrm{L}}=\mathrm{Q} \times \mathrm{R}_{\mathrm{L}}$. Therefore, $\mathrm{X}_{\mathrm{L}}=3.18 \times 4.5=14.31 \Omega$.
Now, $X_{C}=R_{G} / Q=50 / 3.18=15.72 \Omega$.
$\mathrm{L}=\mathrm{X}_{\mathrm{L}} / 2 \pi \mathrm{f}=14.31 /\left(2 \times 3.14 \times 13.56 \times 10^{6}\right)=168 \mathrm{nH}$.
$\mathrm{C}=1 / 2 \pi \mathrm{f} \mathrm{X}_{\mathrm{C}}=1 /\left(2 \times 3.14 \times 13.56 \times 10^{6} \times 15.72\right)=750 \mathrm{pF}$.

## IV. DESIGN OF THE OUTPUT CIRCUIT

## A. To design the output matching circuit of high pass type:

From the manufacturer's data of MRF151, output impedance $\mathrm{Z}_{22}=(7-\mathrm{j} 3.4) \Omega$ and $\mathrm{R}_{\mathrm{L}}=50 \Omega$. The source impedance is $(7-\mathrm{j} 3.4) \Omega$ and the load impedance is $(50+\mathrm{j} 0) \Omega$. L -section is used for the impedance matching.
As $\mathrm{R}_{\mathrm{L}}>\mathrm{R}_{\mathrm{G}}, Q=\sqrt{\frac{R_{L}}{R_{g}}-1}$.
Using given values of $\mathrm{R}_{\mathrm{G}}$ and $\mathrm{R}_{\mathrm{L}}$ we get, $\mathrm{Q}=2.48$.
$\mathrm{X}_{\mathrm{C}}=\mathrm{Q} \times \mathrm{R}_{\mathrm{G}}=2.48 \times 7=17.35 \Omega$.
$\mathrm{X}_{\mathrm{L}}=\mathrm{R}_{\mathrm{L}} / \mathrm{Q}=50 / 2=20.16 \Omega$.
$\mathrm{L}=\mathrm{X}_{\mathrm{L}} / 2 \pi \mathrm{f}=20.16 /\left(2 \times 3.14 \times 13.56 \times 10^{6}\right)=237 \mathrm{nH}$.
$\mathrm{C}=1 / 2 \pi \mathrm{f} \mathrm{X}_{\mathrm{C}}=1 /\left(2 \times 3.14 \times 13.56 \times 10^{6} \times 17.35\right)=677 \mathrm{pF}$.


Figure 2: Circuit of output impedance matching of high pass type

## B. To design the output matching circuit of low pass type:

As the manufacturer's data, basic circuit configuration and the concept remains unchanged therefore $\mathrm{Q}=2.48$ w.r.t. the high pass type matching circuit. Now,
$\mathrm{X}_{\mathrm{L}}=\mathrm{Q} \times \mathrm{R}_{\mathrm{G}}=2.48 \times 7=17.35 \Omega$.
$\mathrm{X}_{\mathrm{C}}=\mathrm{R}_{\mathrm{L}} / \mathrm{Q}=50 / 2=20.16 \Omega$.
$\mathrm{L}=\mathrm{X}_{\mathrm{L}} / 2 \pi \mathrm{f}=17.35 /\left(2 \times 3.14 \times 13.56 \times 10^{6}\right)=204 \mathrm{nH}$.
$\mathrm{C}=1 / 2 \pi \mathrm{f}_{\mathrm{C}}=1 /\left(2 \times 3.14 \times 13.56 \times 10^{6} \times 20.16\right)=583 \mathrm{pF}$.


Figure 3: Circuit of output impedance matching of low pass type

## V. Simulation of the input circuit

In L-section impedance matching i.e. L1 $=184 \mathrm{nH}$ and $\mathrm{C} 2=820 \mathrm{pF}$ should provide maximum power transfer at the frequency of operation. The input power $P_{\text {in }}=10 \mathrm{~mW}$ is impedance matched and found transferring the output power $P_{\text {out }}=10 \mathrm{~mW}$ as shown in Figure 4. This is observed that,

At the $50 \Omega$ source impedance when $\mathrm{V}_{\text {peak }}=1 \mathrm{~V}$ the Power $=$ $\mathrm{V}_{\text {peak }}{ }^{2} / \mathrm{R}=(1 / \sqrt{2})^{2} / 50=0.01 \mathrm{~W}$.

At the $4.5 \Omega$ MOSFET input when $\mathrm{V}_{\text {peak to peak }}=600.82 \mathrm{mV}$, the power $=\mathrm{V}_{\mathrm{p}-\mathrm{p}}^{2} / 8 \mathrm{R}=\left(600.82 \times 10^{-3}\right)^{2} /(8 \times 4.5)=0.01 \mathrm{~W}$.


Figure 4: Power transfer of the input side circuit in the TINA-TI software

## VI. Simulation of the output circuit

For maximum power transfer $\mathrm{L} 1=250 \mathrm{nH}$ and $\mathrm{C} 2=640 \mathrm{pF}$ are used as L-section. In Figure 5, the input power $\mathrm{P}_{\mathrm{in}}=10 \mathrm{~mW}$ and the output power is $P_{\text {out }}=10 \mathrm{~mW}$. By using the calculated value of the L1 and C2, the maximum power is transferred. This is observed that,

At the $50 \Omega$ when $\mathrm{V}_{\text {peak }}=1 \mathrm{~V}$, the Power $=(1 / \sqrt{2})^{2} / 50=0.01 \mathrm{~W}$ At the output impedance of MOSFET $7 \Omega$ when $\mathrm{V}_{\text {peak to peak }}=$ 708.48 mV , the Power $=\left(708.48 \times 10^{-3}\right)^{2} /(8 \times 7)=0.01 \mathrm{~W}$.


Figure 5: Power transfer in the output side circuit in the TINA-TI software

## VII. DESIGN AND SIMULATION OF THE BIASING CIRCUIT

## A. Input Biasing Circuit

The input biasing circuit is shown in the Figure 6. The 2.24 V and 1.15 V voltage variation is required and optimized by using the $10 \mathrm{~K} \Omega$ potentiometer ( P 1 ), $10 \mathrm{~K} \Omega(\mathrm{R} 1)$ and $470 \Omega$ (R3). We could get 2.24 V and 1.15 V at the output when $0 \%$ and $100 \%$ is set in the potentiometer as shown in the Figure 6 and 7 respectively.


Figure 6: Input biasing circuit with $0 \%$ setting in the potentiometer


Figure 7: Input biasing circuit with $100 \%$ setting in the potentiometer

## B. Output biasing circuit

The components C7, C8, C9, C10 and R8 are used in the output biasing circuit. The value of R 8 is calculated as following,
The estimated Efficiency $=\frac{P_{\text {out }(a c)}}{P_{\text {in }(d c)}}=50 \%$ whereas the $\mathrm{P}_{\text {out }}(\mathrm{ac})$ $=100 \mathrm{~W}$ thus $\mathrm{P}_{\mathrm{in}}(\mathrm{dc})=200 \mathrm{~W}$.

Now, $P_{\text {in }}(d c)=V_{D D} \times I_{D}$ thus $200=50 \times I_{D}$ therefore $I_{D}=4 A$.
Now from ohm's law, $\mathrm{R}=\frac{V}{I}=(1 / 4)=0.25 \Omega$.


Figure 8: Schematic of the 100W solid state amplifier

## C. Description of the components used in the amplifier circuit

$\mathrm{C} 3, \mathrm{C} 4, \mathrm{R} 4, \mathrm{R} 3, \mathrm{Z} 1, \mathrm{R} 2, \mathrm{R} 5$ and P1 are the input biasing components whereas $\mathrm{R} 8, \mathrm{C} 7, \mathrm{C} 8, \mathrm{C} 9$ and C 10 are the output biasing components as shown in Figure 8. C1 and C6 capacitors are the coupling capacitors which pass the AC components and block the DC components. C3, C4, C7, C8, C9 and C10 capacitors are used for filtering purpose. C2 capacitor and L1 inductor are the input side matching components. C5 capacitor and L4 inductor are the output side matching components. R1 and R6 resistors are used for stability purpose. R4 resistor is current limiter resistor. Z1 Zener diode and R2 resistor are used as the protected components.
VIII. SIMULATION OF THE POWER AMPLIFIER CIRCUIT


Figure 9: Output matching and output biasing circuits in the TINA TI software

- Here, $\mathrm{R}=50 \Omega$ and Output power $=100 \mathrm{~W}$.
- As $\mathrm{P}=\left(\mathrm{V}^{2} / \mathrm{R}\right)$ therefore $100=\left(\mathrm{V}^{2} / 50\right)$ so $\mathrm{V}=70.71 \mathrm{~V}$.
- $I_{P}=10.75 \mathrm{~A}$ and therefore $\mathrm{I}_{\mathrm{rms}}=\mathrm{I}_{\mathrm{p}} / \sqrt{ } 2=7.60 \mathrm{~A}$.
- When $\mathrm{IG}_{1(\mathrm{rms})}=7.60 \mathrm{~A}$, the output voltage across $50 \Omega$ load $=70.7 \mathrm{~V}$.
- Trans conductance $(\Delta \mathrm{I} / \Delta \mathrm{V})$ for MRF151 $=5 \mathrm{~mA} / \mathrm{V}$ thus, $5=(7.60 / \Delta \mathrm{V})$ and $\Delta \mathrm{V}=(7.60 / 5)=1.52 \mathrm{~V}$.


Figure 10: Input matching and input biasing circuits in the TINA TI software

- $\mathrm{VG}_{1(\mathrm{P})}=14.69 \mathrm{~V}$ thus, $\mathrm{VG}_{1(\mathrm{rms})}=\left(\mathrm{VG}_{1(\mathrm{P})} / \sqrt{ } 2\right)=$ $(14.69 / \sqrt{ } 2)=10.4184 \mathrm{~V}$.
- $\mathrm{P}_{\mathrm{in}}=\left(\mathrm{V}_{\mathrm{in}}{ }^{2} / \mathrm{R}\right)=(10.4184)^{2} / 50=2.1708 \mathrm{~W}$.
- $P_{\text {out }}=100 \mathrm{~W}$.
- Gain $=10 \times \log \left(\mathrm{P}_{\mathrm{out}} / \mathrm{P}_{\text {in }}\right)=16.63 \mathrm{~dB}$.
- $\quad P_{\text {in }(\mathrm{dc})}=\mathrm{V}_{\mathrm{DD}} \times \mathrm{I}_{\mathrm{D}}=50 \times 4=200 \mathrm{~W}$.
- Efficiency $=\mathrm{P}_{\mathrm{out}}(\mathrm{ac}) / \mathrm{P}_{\text {in }}(\mathrm{dc})=50 \%$.


## IX. FABRICATION AND TESTING OF THE 100W SSPA

The circuit is fabricated with MOSFET MRF151 mounted on a heat sink. The input and output circuits are fabricated on 1 mm thick G10 insulation sheets mounted on each side of the MOSFET as shown in Figure 11. A thermal switch in series of the drain supply is mounted on the heat sink to cut off in case of overheating thus protecting the device above $65^{\circ} \mathrm{C}$.


Figure 11: Top view of the 100W SSPA hardware
Signal Generator, Dummy Load, RF Power Amplifier, and DC power supply are used to test the 100W SSPA as shown in Figure 12.


Figure 12: Test set up

TABLE II. TABLE OF THE CIRCUIT PARAMETERS AT PIN OF 0.16W

| Frequency <br> in (MHz) | Input <br> voltage <br> Vpp | Output <br> voltage <br> Vpp | $\mathrm{I}_{\mathrm{D}}$ <br> $(\mathrm{DC})$ <br> $(\mathrm{A})$ | $\mathrm{P}_{\text {in }}$ <br> $(\mathrm{W})$ | $\mathrm{P}_{\text {out }}$ <br> $(\mathrm{W})$ | Gain <br> $(\mathrm{dB})$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 12.5 | 8 | 206 | 3.2 | 0.16 | 106.09 | 28.22 |
| 12.7 | 8 | 210 | 3.2 | 0.16 | 110.25 | 28.38 |
| 12.9 | 8 | 212 | 3.2 | 0.16 | 112.36 | 28.46 |
| 13.1 | 8 | 214 | 3.3 | 0.16 | 114.49 | 28.55 |
| 13.3 | 8 | 216 | 3.3 | 0.16 | 116.64 | 28.63 |
| 13.5 | 8 | 216 | 3.3 | 0.16 | 116.64 | 28.63 |
| 13.7 | 8 | 216 | 3.3 | 0.16 | 116.64 | 28.63 |
| 13.9 | 8 | 212 | 3.2 | 0.16 | 112.36 | 28.46 |


| 14.1 | 8 | 212 | 3.2 | 0.16 | 112.36 | 28.46 |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 14.3 | 8 | 206 | 3.2 | 0.16 | 106.09 | 28.22 |
| 14.5 | 8 | 200 | 3 | 0.16 | 100 | 27.96 |

From the above given Table II, the $\mathrm{P}_{\text {out }}(\mathrm{ac})=116.64 \mathrm{~W}$ and the $P_{\text {in }}(\mathrm{dc})=50 \times 3.3=165 \mathrm{~W}$ at the 13.56 MHz . Therefore,

The efficiency $=\frac{\mathrm{P}_{\text {out }}(\mathrm{ac})}{\mathrm{P}_{\text {in (dc) }}}=70.69 \%$ and the power dissipation $=$ $165-116.64=48.36 \mathrm{~W}$ at the 13.56 MHz .


Figure 13: Waveform at 13.5 MHz with output $\mathrm{V}_{\mathrm{pp}}=216 \mathrm{~V}$ in the DSO

Now, the low pass output circuit is fabricated and used instead of the high pass type in the output matching circuit as shown in the Figure 14.


Figure 14: Circuit fabricated with low pass type of the output matching circuit
The second type of 100W SSPA is tested and results are shown in Table III on the next page. Results of the two different types of circuit with high and low pass output matching circuit are compared.

From the Table III, the $\mathrm{P}_{\text {out }}(\mathrm{ac})=100 \mathrm{~W}$ and the $\mathrm{P}_{\text {in }}(\mathrm{dc})=50 \times$ $3.4=170 \mathrm{~W}$ at the 13.56 MHz . Therefore,

The efficiency $=\frac{\mathrm{P}_{\text {out }}(\mathrm{ac})}{\mathrm{P}_{\text {in }(\mathrm{dc})}}=58.82 \%$ and the power dissipation $=$ $170-100=70 \mathrm{~W}$ at the 13.56 MHz .

TABLE III. TABLE OF THE CIRCUIT PARAMETERS AT PIN OF 0.17W

| Frequency <br> in (MHz) | Input <br> voltage <br> Vpp | Output <br> voltage <br> Vpp | $\mathrm{I}_{\mathrm{D}}$ <br> $(\mathrm{DC})$ <br> $(\mathrm{A})$ | $\mathrm{P}_{\text {in }}$ <br> $(\mathrm{W})$ | $\mathrm{P}_{\text {out }}$ <br> $(\mathrm{W})$ | Gain <br> $(\mathrm{dB})$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| 12.5 | 8.32 | 192 | 3.3 | 0.17 | 92.16 | 27.34 |
| 12.7 | 8.32 | 194 | 3.3 | 0.17 | 94.09 | 27.43 |
| 12.9 | 8.32 | 196 | 3.4 | 0.17 | 96.04 | 27.52 |
| 13.1 | 8.32 | 198 | 3.4 | 0.17 | 98.01 | 27.61 |
| 13.3 | 8.32 | 198 | 3.4 | 0.17 | 98.01 | 27.61 |
| 13.5 | 8.32 | 200 | 3.4 | 0.17 | 100 | 27.7 |
| 13.7 | 8.32 | 200 | 3.4 | 0.17 | 100 | 27.7 |
| 13.9 | 8.32 | 198 | 3.3 | 0.17 | 98.01 | 27.61 |
| 14.1 | 8.32 | 196 | 3.3 | 0.17 | 96.04 | 27.52 |
| 14.3 | 8.32 | 194 | 3.3 | 0.17 | 94.09 | 27.43 |
| 14.5 | 8.32 | 192 | 3.2 | 0.17 | 92.16 | 27.34 |

The wave shape of the output signal and the bandwidth flatness is improved in the low pass type of the output matching circuit in comparison with the high pass type of the output matching circuit. The Efficiency is decreased in the low pass type of the output matching circuit compare to the high pass type of the output matching circuit.


Figure 15: Waveform at 13.5 MHz with output $\mathrm{V}_{\mathrm{pp}}=200 \mathrm{~V}$ in the DSO

## Conclusion

This is concluded that selection of proper MOSFET with stability parameters of $K=3.1$ is done based on the required specification. The impedance matching circuit and the biasing circuit were designed for optimum performance. The simulation results are found in agreement with the desired specification. All the components are fabricated on the G10 and the complete circuit was tested in the required frequency bandwidth of $13.56 \pm 1 \mathrm{MHz}$. After proper optimization of the matching circuit the desired output (100W) was obtained at
13.56 MHz . The response was within 0.36 dB over the specified bandwidth.

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